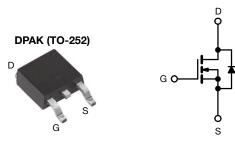


E Series Power MOSFET



N-Channel MOSFET

PRODUCT SUMMARY			
V _{DS} (V) at T _J max.	850		
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	1.1	
Q _g max. (nC)	32		
Q _{gs} (nC)	4		
Q _{gd} (nC)	6		
Configuration	Single		

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION		
Package	DPAK (TO-252)	
	SiHD4N80E-GE3	
Load (Dh) free and belonen free	SiHD4N80ET1-GE3	
Lead (Pb)-free and halogen-free	SiHD4N80ET4-GE3	
	SiHD4N80ET5-GE3	

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	800	V
Gate-source voltage			V_{GS}	± 30	7 v
Continuous drain current (T, = 150 °C)	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	I-	4.3	
Continuous drain current (1) = 150 C)	VGS at 10 V	T _C = 100 °C	I _D	2.7	Α
Pulsed drain current ^a			I _{DM}	11	
Linear derating factor			0.56	W/°C	
Single pulse avalanche energy b		E _{AS}	56	mJ	
Maximum power dissipation		P_{D}	69	W	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope T _J = 125 °C		dv/dt	70	V/ns	
Reverse diode dv/dt ^d			0.3	V/IIS	
Soldering recommendations (peak temperature) ^c For 10 s			300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 2.0 A
- c. 1.6 mm from case
- d. $I_{SD} \leq I_{D}$, di/dt = 100 A/ μ s, starting T_{J} = 25 °C



Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	1.8	C/VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	800	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	1.1	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Onto anima lankana			$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
7		V _{DS} =	= 800 V, V _{GS} = 0 V	-	-	1	μA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 640 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 2 A	-	1.1	1.27	Ω
Forward transconductance	9 _{fs}	V _{DS}	s = 30 V, I _D = 2 A	-	1.5	-	S
Dynamic							•
Input capacitance	C _{iss}		V _{GS} = 0 V,	-	622	-	_
Output capacitance	C _{oss}		$V_{DS} = 100 \text{ V},$	-	34	-	
Reverse transfer capacitance	C _{rss}		f = 1 MHz	-	5	-	
Effective output capacitance, energy related ^a	C _{o(er)}		V _{DS} = 0 V to 480 V, V _{GS} = 0 V		21	-	pF
Effective output capacitance, time related ^b	C _{o(tr)}	V _{DS} = 0 \			91	-	
Total gate charge	Qg			-	16	32	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 2 \text{ A}, V_{DS} = 480 \text{ V}$		4	-	nC
Gate-drain charge	Q _{gd}			-	6	-	
Turn-on delay time	t _{d(on)}			-	12	24	
Rise time	t _r	V _{DD} = 480 V, I _D = 2 A,		-	7	14	
Turn-off delay time	t _{d(off)}		$V_{DD} = 460 \text{ V}, I_D = 2 \text{ A},$ $V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		26	52	ns
Fall time	t _f				20	40	
Gate input resistance	R _g	f = 1 MHz, open drain		0.6	1.2	2.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	4.4	
Pulsed diode forward current	I _{SM}			-	-	11	A
Diode forward voltage	V_{SD}	T _J = 25 °	T _J = 25 °C, I _S = 2 A, V _{GS} = 0 V		-	1.2	V
Reverse recovery time	t _{rr}	-	0 1 17 0 7 do 1		248	496	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 2 \text{A},$ di/dt = 100 A/ μ s, $V_R = 25 \text{V}$		-	1.4	2.8	μC
Reverse recovery current	I _{RRM}			-	9.2	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

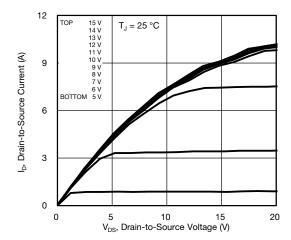


Fig. 1 - Typical Output Characteristics

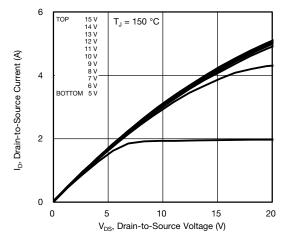


Fig. 2 - Typical Output Characteristics

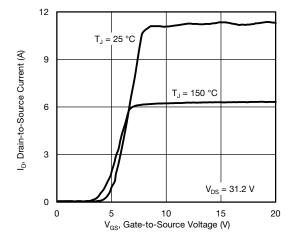


Fig. 3 - Typical Transfer Characteristics

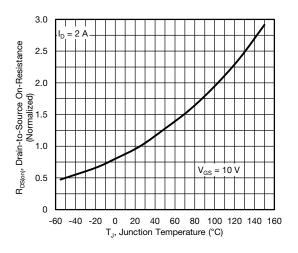


Fig. 4 - Normalized On-Resistance vs. Temperature

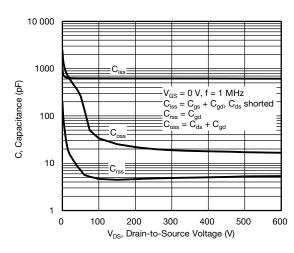


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

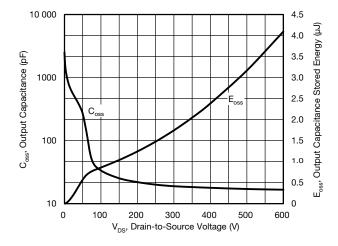


Fig. 6 - Coss and Eoss vs. VDS



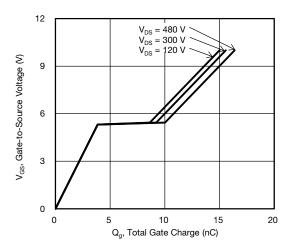


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

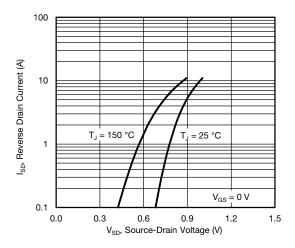


Fig. 8 - Typical Source-Drain Diode Forward Voltage

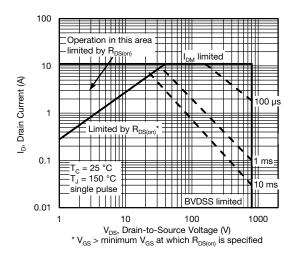


Fig. 9 - Maximum Safe Operating Area

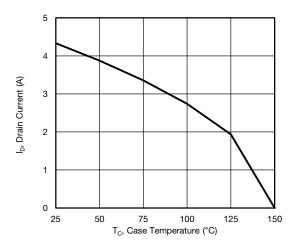


Fig. 10 - Maximum Drain Current vs. Case Temperature

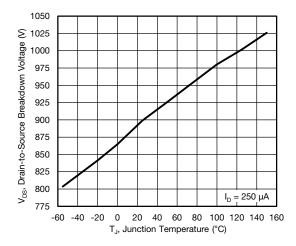


Fig. 11 - Temperature vs. Drain-to-Source Voltage



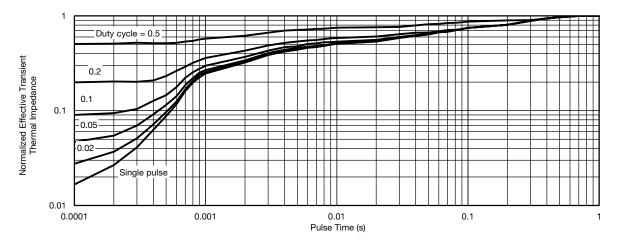


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

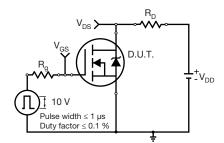


Fig. 13 - Switching Time Test Circuit

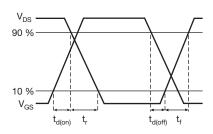


Fig. 14 - Switching Time Waveforms

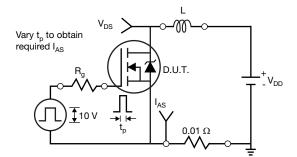


Fig. 15 - Unclamped Inductive Test Circuit

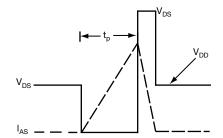


Fig. 16 - Unclamped Inductive Waveforms

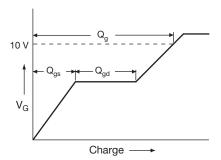


Fig. 17 - Basic Gate Charge Waveform

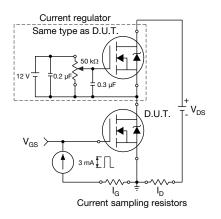
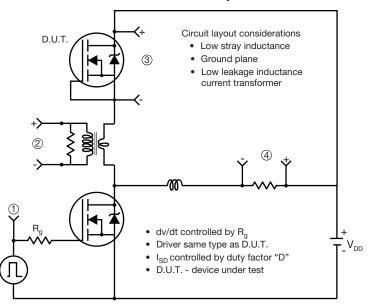




Fig. 18 - Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



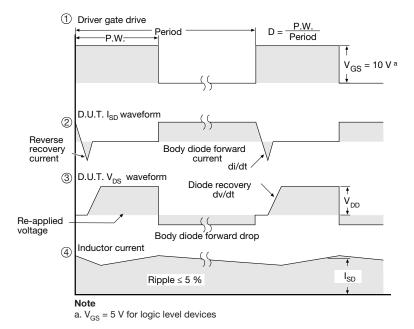


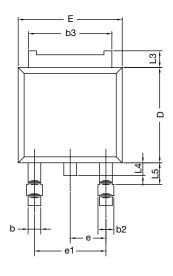
Fig. 19 - For N-Channel

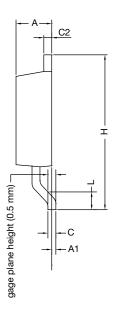
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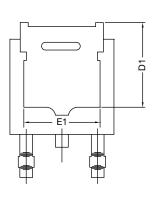


TO-252AA Case Outline

VERSION 1: FACILITY CODE = Y







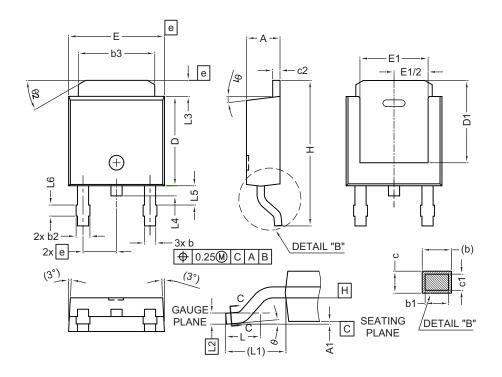
	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.38	
A1	-	0.127	
b	0.64	0.88	
b2	0.76	1.14	
b3	4.95	5.46	
С	0.46	0.61	
C2	0.46	0.89	
D	5.97	6.22	
D1	4.10	-	
Е	6.35	6.73	
E1	4.32	=	
Н	9.40	10.41	
е	2.28 BSC		
e1	4.56 BSC		
L	1.40	1.78	
L3	0.89	1.27	
L4	-	1.02	
L5	1.01	1.52	

Note

• Dimension L3 is for reference only



VERSION 2: FACILITY CODE = N



	MILLIMETERS		
DIM.	MIN.	MAX.	
Α	2.18	2.39	
A1	-	0.13	
b	0.65	0.89	
b1	0.64	0.79	
b2	0.76	1.13	
b3	4.95	5.46	
С	0.46	0.61	
c1	0.41	0.56	
c2	0.46	0.60	
D	5.97	6.22	
D1	5.21	=	
Е	6.35	6.73	
E1	4.32	=	
е	2.29 BSC		
Н	9.94	10.34	

	MILLIMETERS		
DIM.	MIN.	MAX.	
L	1.50	1.78	
L1	2.74	ref.	
L2	0.51	BSC	
L3	0.89	1.27	
L4	-	1.02	
L5	1.14	1.49	
L6	0.65	0.85	
θ	0°	10°	
θ1	0°	15°	
θ2	25°	35°	

Notes

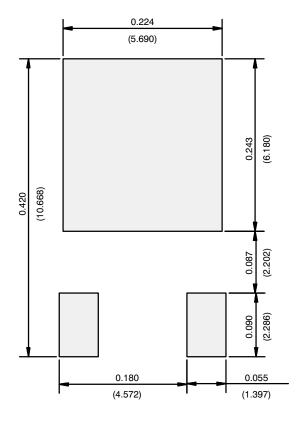
- Dimensioning and tolerance confirm to ASME Y14.5M-1994
- All dimensions are in millimeters. Angles are in degrees
- Heat sink side flash is max. 0.8 mm
- · Radius on terminal is optional

ECN: E22-0399-Rev. R, 03-Oct-2022

DWG: 5347



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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